

.....Kulicke & Soffa Launches Next Generation Manual Wire Bonder Series

SINGAPORE--(BUSINESS WIRE)--

Kulicke & Soffa Industries, Inc. (KLIC) ("K&S" or the "Company") today announced the launch of its next generation manual wire bonder series, the iBond5000™. The advanced series is the next creation from the proven market leader with over 60 years of experience in wire bonding, and over 9000 manual machines installed worldwide. The series is based on the Company's 4500, and integrates the proven legacy K&S mechanical design with advanced electronics to provide modern capabilities. The iBond5000 series includes ball, wedge and dual-capability bonding options.

From September 5-7, customers can see the feature rich iBond5000 in action, throughout SEMICON Taiwan in Booth #780, Floor 4. The iBond5000Ball, iBond5000Wedge, and iBond5000Dual are advanced bonders used for process development, production, research and added manufacturing support. They provide the excellent yield and repeatability needed for high-end applications including: Optoelectronic Modules, Hybrids/MCMs, Microwave Products, Discrete Devices/Lasers, Chip-on-boards, Leads, Sensors, High Power Devices and much more.

Improved features of the iBond5000 include the addition of a multi-core ARM based processor, proven operating system and 7" touch screen. With the improved electronics management, there are also more ways to connect to the iBond5000 via two USB ports for a mouse, keyboard or disk on key; or via Ethernet which allows for centralized management, access to an applications backup server, and capability for remote support and profile sharing. For those that prefer working with physical controls, an optional analog panel is available. The system enables saving and loading of custom files, along with factory preconfigured profiles, for storing, cataloging, and re-using golden processes. The K&S bonding profiles internal library, which includes a bonding wires database, will enhance the ease of use and cater for various applications. The iBond5000 has an abundance of advanced options for improved efficiency and expertise, while also lowering cost of ownership.

Aviram Shubeli, Kulicke & Soffa's Manual Wire Bonding Business Unit Manager, remarked, "The iBond5000 offers customers important advancements, features and increased benefits all of which leverage K&S' market leadership, R&D strength and process knowledge. We designed the iBond5000 to embody today's modern digital technologies, while expanding upon the proven high standards from our existing wire bonder solutions."

About Kulicke & Soffa

Kulicke & Soffa (KLIC) is a global leader in the design and manufacture of semiconductor and LED assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions, adding die and wedge bonders and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

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